



Material Content Data Sheet



Sales Product Name				BTN8982TA		Issued		25. January 2018	
MA#				MA002167814					
Package				PG-TO263-7-1		Weight*		1532.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	4.086	0.27	0.27	2666	2666	
chip_2	inorganic material	silicon	7440-21-3	4.086	0.27	0.27	2666	2666	
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	791	791	
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158		
	non noble metal	iron	7439-89-6	0.810	0.05		528		
	non noble metal	copper	7440-50-8	808.613	52.76	52.83	527574	528260	
wire	non noble metal	aluminium	7429-90-5	6.176	0.40	0.40	4029	4029	
encapsulation	organic material	carbon black	1333-86-4	8.761	0.57		5716		
	plastics	epoxy resin	-	96.369	6.29		62875		
	inorganic material	silicondioxide	60676-86-0	478.924	31.25	38.11	312471	381062	
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8506	8506	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140	
solder	non noble metal	tin	7440-31-5	0.066	0.00		43		
	noble metal	silver	7440-22-4	0.082	0.01		54		
	non noble metal	lead	7439-92-1	3.141	0.20	0.21	2049	2146	
glue	plastics	Polyimide	26023-21-2	0.533	0.03	0.03	348	348	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		69		
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69296	69386	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com